

## **Product Information Sheet**

**EPO-TEK® B13181** 

Date: December 2023 Recommended Cure: B-stage cure: 80°C/30 Minutes

Rev: | Cure: 150°C/1 Hour

No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.46
Pot Life: 28 Days

Shelf Life- Bulk: One year @ -40°C

## NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, thermally conductive, low-halogen, B-Stage Epoxy Paste

**Typical Properties:** Cure condition: B-stage cure: 80°C/30 Minutes - Cure: 150°C/1 Hour Data below is not guaranteed. Different batches, conditions & applications yield differing results. To be used as a guide only, not as a specification.

\* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
Color (before cure):	Tan		
Consistency:	Smooth, slightly thixotropic paste		
Viscosity (23°C) @ 1 rpm:	40,960	cPs	
Thixotropic Index:	1.5		
Glass Transition Temp:	123	°C	
Die Shear @ 23°C:	28	Kg	(ceramic die on glass)
Die Shear @ 23°C:	25	Kg	(ceramic die on Kovar)
Degradation Temp:	391	°Č	
Weight Loss:			
@ 200°C:	0.82	%	
@ 250°C:	1.75	%	
@ 300°C:	3.45	%	
Suggested Operating Temperature:	< 250	°C (I	ntermittent)
Particle Size:	≤ 20	micro	ons

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	TBD	W/mK